

CLAIMS

1. A method for transferring a device, comprising the steps of:
irradiating, selectively, an interface between a first substrate and a device included on the first substrate with an energy beam and transmitting the energy beam through the first substrate to selectively release the device;
transferring the released device onto a device holding layer included on a device holding substrate; and
transferring the device from the device holding layer onto a second substrate.
2. A method for transferring a device as claimed in claim 1, further comprising the step of cleaning the device on the device holding layer after the device is transferred onto the device holding layer.
3. A method for transferring a device as claimed in claim 1, further comprising the step of providing an adhesive layer on the second substrate wherein the adhesive layer is irradiated with the energy beam when the device is transferred from the device holding layer onto the second substrate.
4. A method for transferring a device as claimed in claim 1, wherein the device is formed of a material which produces ablation upon irradiation with the energy beam, and wherein ablation is generated by the selective irradiation with the energy beam to cause exfoliation at an interface between the device and the first substrate.
5. A method for transferring a device as claimed in claim 4, wherein the material is a nitride semiconductor material.
6. A method for transferring a device as claimed in claim 5, wherein the nitride semiconductor material is a GaN-based material.
7. A method for transferring a device as claimed in claim 1, wherein the first substrate is a sapphire substrate.

8. A method for transferring a device as claimed in claim 1, wherein the device has one of a pointed head portion and a flat plate-shaped structure.

9. A method for transferring a device as claimed in claim 1, wherein the device is a light-emitting device.

10. A method for transferring a device as claimed in claim 1, wherein the device has a pointed head portion, and the device holding layer includes a surface with a recessed portion shaped to fit the pointed head portion.

11. A method for transferring a device as claimed in claim 1, wherein the device holding layer is a silicone resin layer.

12. A method for producing a device holding substrate, comprising the steps of:

preparing a substrate that includes a device having a pointed head portion;
providing an uncured silicone resin layer on a device holding substrate;
adhering the substrate that includes the device having the pointed head portion to the device holding substrate; and

providing a recessed portion in a surface of the silicone resin layer shaped to fit the pointed head portion.

13. A method for producing a device holding substrate as claimed in claim 12, wherein the device is coated with a release agent before the step of adhering the substrate that includes the device having the pointed head portion to the device holding substrate.

14. A device holding substrate, comprising:
a substrate;

and a silicone resin layer provided on the substrate,

wherein a surface of the silicone resin layer has a

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